



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 4, 2011

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231 Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006 Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

STATUS REQUEST

Sir:

An RCE was filed in the above application on April 5, 2010. To date, the undersigned attorney of record has not received an Office Action. Please advise the undersigned attorney of record of the status concerning the above-referenced application as soon as possible.

Respectfully submitted,


Terryence F. Chapman

TFC/smd

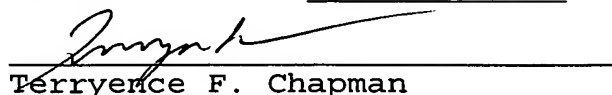
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April 4, 2011.


Terryence F. Chapman